

## EPG 2601[M]

ADBOND EPG 2601M is formulated for bonding of honeycomb structures and capable of working under harsh space environments such as thermo-vacuum, thermal cycling, radiation etc. The main feature of this material is that it is thermally conducting and can retain its property at very low temperatures.

ADBOND EPG 2601M is a two part chemically reactive epoxy structural adhesive system consists of polyether modified epoxide resin, filler, rheological additive and colorant in the resin part, curing agent and accelerator in the hardener part. Cure is achieved by mixing the hardener part with resin part packed separately.

Some of the specialties of this material are minimum cure shrinkage combined with excellent adhesion, superior strength & toughness and low out gassing Typical properties/ characteristics

1	Color& consistency	Part A: Black, viscous resin, Part B: Brownish yellow
2	Viscosity (ps)	1000 to 4000
3	Sp. Gravity	1.65
4	Hardness (Shore D)	≥70
5	Lap shear strength (ksc) on Alumina at RT	120
6	Thermal conductivity (cal/cm/C/s)	$8 \times 10^{-4}$

7	Coef. of thermal expansion (/ oC)	$3.5 \times 10^{-5} - 10 \times 10^{-5}$
7	Volume Resistivity (ohm- cm)	$6 \times 10^{12}$
8	Out gassing	
9	- TML (%)	1
10	- CVCM (%)	0.05
11	Service temperature	93 K to 373 K